

New

Outline

I have JPEG pre disposal, the analog video signal output(D/A converter)built-in, and realize high quality picture by high-speed monitoring by hardware disposal(30field/sec)and original image revision circuit.

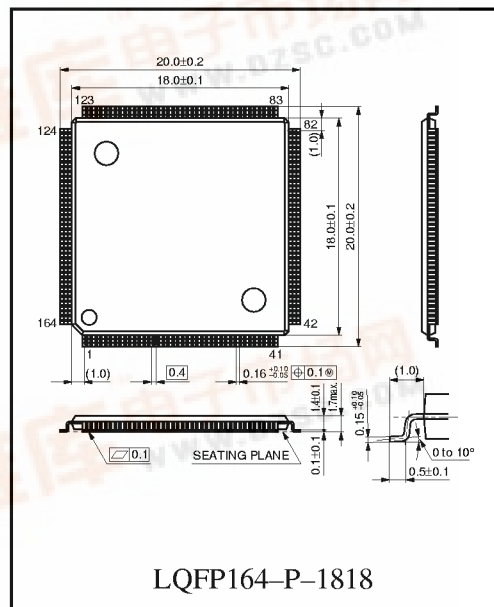
- I adopt RGB signal processing system which was superior in color reproduction.
- I realize high quality picture by 5 line signal processing technology that line memory is built in.
- I have 10 bits D/A converter(3ch)built-in, and respond to RGB output and the video output.
- DCT interface circuit deployment
- RGB interface circuit deployment
- I have TG/SSG circuit, digital encoder built-in
- for NTSC and PAL
- input: Digital input signal 10bit
output: analog composite output, the analog component output
input and output: DCT interface 8 bits digital
- Recommendation operating frequency 24.5454MHz(NTSC)
29.5000MHz(PAL)
- Recommendation operating power supply voltage $3.3V \pm 0.3V$

- digital still camera

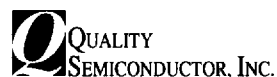
Diagram of system block

The diagram illustrates the system block architecture for the MN67328. The central component is the MN67328 chip, which contains several functional blocks: DSP, Digital encoder, D/A, TG/SSG, Memory controller, DCT I/F, and RGB I/F. The input path starts with a V-Drive (MN3113F) connected to a CCD (MN3777PT) and a VGA input. The signal then passes through a CDS (AN2108FHP) and an A/D converter (AN8133FHP) before entering the DSP block. The DSP output goes to the Digital encoder, which then connects to the D/A converter. The D/A converter has two outputs: an Analog output to a TV and an RGB output to an LCD. The DSP also has a TG/SSG block connected to it. The Memory controller is connected to the DSP and the DCT I/F block. The DCT I/F block is connected to the D/A converter and the JPEG block. The JPEG block is connected to the DCT I/F block and the Flash memory. The Flash memory is connected to the JPEG block. The system also includes an 8-bit microcomputer (MN101C01D) connected to the DSP, an EEPROM, and a DRAM (4M-bit x 2) connected to the Memory controller.

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graph LR
    VDrive[V-Drive  
MN3113F] --> CCD[CCD  
MN3777PT  
VGA]
    CCD --> CDS[CDS  
AN2108FHP]
    CDS --> AD[A/D  
AN8133FHP]
    AD --> DSP[DSP]
    DSP --> DE[Digital encoder]
    DE --> DA[D/A]
    DA --> TV[To TV]
    DA --> LCD[To LCD]
    DSP --> TGSSG[TG/SSG]
    DSP --> MC[Memory controller]
    MC --> DCTIF[DCT I/F]
    DCTIF --> JPEG[JPEG]
    JPEG --> Flash[Flash memory]
    Micro[8-bit microcomputer  
MN101C01D] --> DSP
    Micro --> EEPROM[EEPROM]
    DRAM[DRAM  
4M-bit x 2] --> MC
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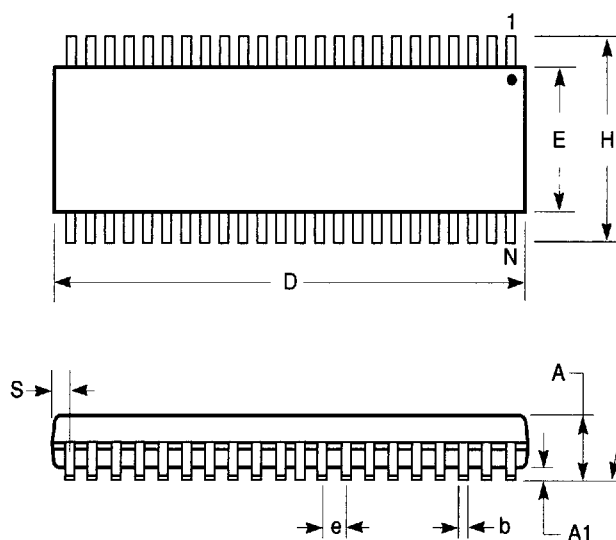


Selection Guide and Packaging Information



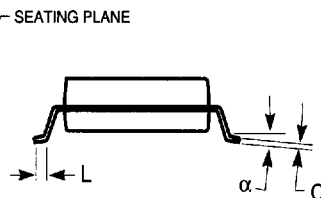
300-MIL SSOP - Package Code PV

Shrink Small Outline Package
Plastic Small Outline Gull-Wing



Notes:

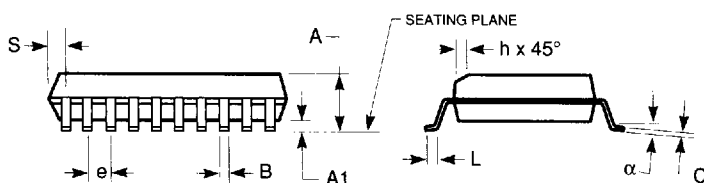
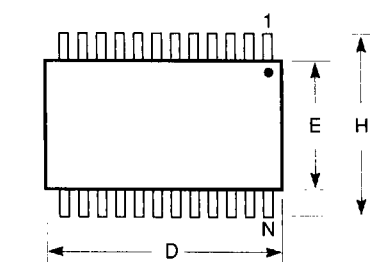
1. Refer to applicable symbol list.
2. All dimensions are in inches.
3. N is the number of lead positions.
4. Dimensions D and E are to be measured at maximum material condition but do not include mold flash. Allowable mold flash is 0.006in. per side.
5. Lead coplanarity is 0.004in. maximum.



JEDEC#	MO-118AA			MO-118AB		
DWG#	PSS-48B			PSS-56B		
Symbol	Min	Nom	Max	Min	Nom	Max
A	0.095	0.102	0.110	0.095	0.102	0.110
A1	0.008	0.012	0.016	0.008	0.012	0.016
b	0.008	0.010	0.0135	0.008	0.010	0.0135
C	0.005	0.008	0.010	0.005	0.008	0.010
D	0.620	0.625	0.630	0.720	0.725	0.730
E	0.291	0.295	0.299	0.291	0.295	0.299
e	0.025 BSC			0.025 BSC		
H	0.395	0.410	0.420	0.395	0.410	0.420
L	0.020	0.030	0.040	0.020	0.030	0.040
N	48			56		
α	0°	5°	8°	0°	5°	8°
S	0.022	0.025	0.028	0.022	0.025	0.028

170-MIL TSSOP - Package Code PA

Thin Shrink Small Outline Package
Plastic Small Outline Gull-Wing



Notes:

1. Refer to applicable symbol list.
2. N is the number of lead positions.
3. Dimensions D and E are to be measured at maximum material condition but do not include mold flash. Allowable mold flash is 0.006in. per side.
4. Lead coplanarity is 0.004in. maximum.

JEDEC#	MO-153AD			MO-153AD		
DWG#	PSS-24C			PSS-24C		
Symbol	Min	Nom	Max	Min	Nom	Max
A	0.045	0.046	0.047	1.14	1.17	1.20
A1	0.002	0.004	0.006	0.05	0.10	0.15
b	0.007	0.010	0.012	0.19	0.25	0.30
C	0.004	0.005	0.006	0.09	0.13	0.16
D	0.303	0.307	0.311	7.7	7.8	7.9
E	0.169	0.173	0.177	4.3	4.4	4.5
e	0.025 BSC			0.65 BSC		
H	0.238	0.252	0.269	6.1	6.4	6.7
L	0.020	0.024	0.030	0.50	0.60	0.75
N	24			24		
α	0°	5°	8°	0°	5°	8°
S	0.007	0.008	0.009	0.18	0.2	0.22

IN INCHES

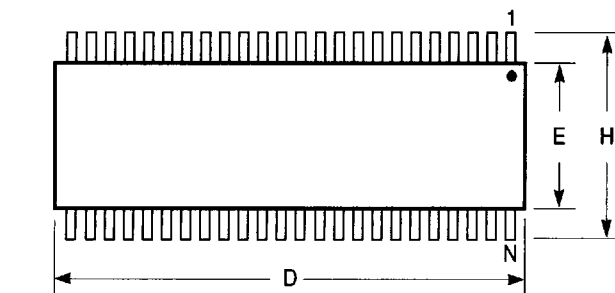
IN MILLIMETERS

Selection Guide and Packaging Information



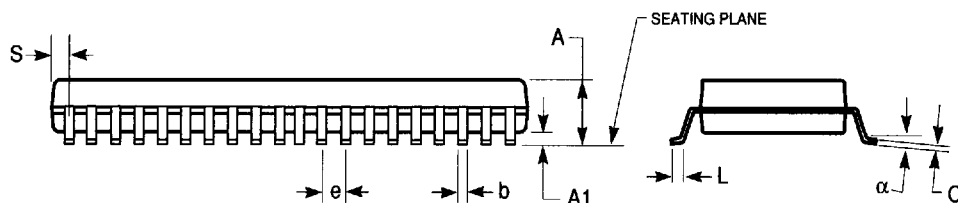
240-MIL TSSOP - Package Code PA

Thin Shrink Small Outline Package
Plastic Small Outline Gull-Wing



Notes:

1. Refer to applicable symbol list.
2. N is the number of lead positions.
3. Dimensions D, E, and S are to be measured at maximum material condition but do not include mold flash. Allowable mold flash is 0.006 in. per side.
4. Lead coplanarity is 0.004in. maximum.



JEDEC#	MO-153ED			MO-153EE			MO-153ED			MO-153EE		
DWG#	PSS-48C			PSS-56C			PSS-48C			PSS-56C		
Symbol	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
A	0.039	0.043	0.047	0.039	0.043	0.047	1.00	1.10	1.20	1.00	1.10	1.20
A1	0.002	0.004	0.006	0.002	0.004	0.006	0.05	0.10	0.15	0.05	0.10	0.15
b	0.006	0.008	0.011	0.006	0.008	0.011	0.17	0.20	0.27	0.17	0.20	0.27
C	0.004	0.006	0.008	0.004	0.006	0.008	0.09	0.15	0.20	0.09	0.15	0.20
D	0.488	0.492	0.496	0.547	0.551	0.555	12.40	12.50	12.60	13.90	14.00	14.10
E	0.236	0.240	0.244	0.236	0.240	0.244	6.00	6.10	6.20	6.00	6.10	6.20
e	0.0197 BSC			0.0197 BSC			0.50 BSC			0.50 BSC		
H	0.315	0.319	0.323	0.315	0.319	0.323	8.00	8.10	8.20	8.00	8.10	8.20
L	0.018	0.024	0.030	0.018	0.024	0.030	0.45	0.60	0.75	0.45	0.60	0.75
N	48			56			48			56		
α	0°	5°	8°	0°	5°	8°	0°	5°	8°	0°	5°	8°
S	0.015	0.020	0.025	0.006	0.010	0.014	0.38	0.50	0.65	0.15	0.25	0.35

DIMENSIONS IN INCHES

DIMENSIONS IN MILLIMETERS